Hot Air Reflow Soldering Recommendations:

Pb-Free Process – Classification Temperatures (Tc)			
Package Thickness	Volume mm³ <350	Volume mm³ 350~2000	Volume mm³ > 2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245° C

Only for devices with a package thickness < 2.5 mm and a package volume < 350 mm³

Profile Feature	Pb-Free
Preheat Time (150 °C ~200 °C)	60-120 s
Ramp-up rate	≤3 °C /s
Liquidous temperature > 217 °C	60-150 s
Peak package body temperature	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	30 s
Ramp-down rate	≤6 °C/s
Time 25 °C to peak temperature	≤480 s